PROCESS FOR CONTROLLIONG RESISN BLEEDIKNG IN INTEGRATED CIRCUIT PACKAGING

Abstract of the Invention

A method for controlling resin bleeding on integrated circuit packages is disclosed. Resin bleeding is controlled by lowering the surface energy of an IC substrate to less than or about equal to the surface energy of an adhesive which attaches IC units thereto. The IC substrate is treated with a material that lowers its surface energy. The material layer forms a less wettable surface on the IC substrate which inhibits resin bleeding when the adhesive applied thereto is hardened. The material layer is formed from a solution of a polymer in a solvent. Suitable polymers include polyfluorinated hydrocarbon compounds.

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